

ET1826

End Termination

Description

ET1826 is a solderable Ag/Pt end termination designed for use on MLCC (multilayer ceramic chip capacitors). ET1826 offers excellent solderability and adhesion. ET1826 is supplied at a viscosity suitable for machine dip and blot or no blot applications

Key Features

- Suitable rheology for machine dip application
- Excellent solderability and adhesion
- Compatible on titanate ceramic bodies



This picture does not show the packaging of ET1826 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	25-35 Kcps Brookfield RVT SC4-14 spindle, 6R utility cup at 10 rpm, 25 °C
Metal	AgPt

Recommended Processing Guide

Process Temperature (TDS)	780-810 °C at peak temperature. Dwell time of 5-6 minutes at peak.
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